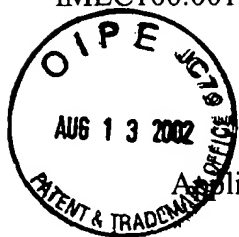


#4/Amolt A  
8.28.02  
C Moore

## PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

) Group Art Unit 2814

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

August 8, 2002

\_\_\_\_\_  
(Date)  
\_\_\_\_\_  
Rose M. Thiessen, Reg. No. 40,202

;

RECEIVED  
AUG 22 2002  
TECHNOLOGY CENTER 2800

Dear Sir:

In response to the Office Action mailed February 27, 2002 Applicants respectfully request that the Examiner enter the following amendments and consider the following remarks.

IN THE CLAIMS:

Please amend Claims 1-10 as follows:

1. (Amended) A method for forming a patterned hard mask layer in an organic polymer film for an interconnect structure in an integrated circuit, said method comprising:
- fluorinating a part of an organic polymer film, thereby forming a fluorinated part, said fluorinated part forming a first hard mask layer;
  - forming a patterned second hard mask layer on said film;
  - patterning said first hard mask layer using said patterned second hard mask layer as a mask, thereby forming a patterned first hard mask layer;